

Title (en)
METHODS AND APPARATUS FOR HOLDING AND POSITIONING SEMICONDUCTOR WORKPIECES DURING ELECTROPOLISHING AND/OR ELECTROPLATING OF THE WORKPIECES

Title (de)
VERFAHREN UND VORRICHTUNG ZUR HALTERUNG UND POSITIONIERUNG VON HALBLEITERWERKSTÜCKEN BEIM ELEKTROPOLIEREN UND/ODER ELEKTROPLATTIEREN VON HALBLEITERWERKSTÜCKEN

Title (fr)
PROCEDES ET APPAREILS DEUPPORT ET DE POSITIONNEMENT DE PIECES A SEMICONDUCTEURS LORS DE LEUR POLISSAGE ELECTROLYTIQUE ET/OU DE LEUR PLACAGE PAR ELECTRODEPOSITION

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Application
EP 99965053 A 19991124

Priority
• US 9928106 W 19991124
• US 11013698 P 19981128

Abstract (en)
[origin: WO0033356A2] A wafer chuck assembly for holding a wafer during electroplating and/or electropolishing of the wafer includes a wafer chuck for receiving the wafer. The wafer chuck assembly also includes an actuator assembly for moving the wafer chuck between a first and a second position. When in the first position, the wafer chuck is opened. When in the second position, the wafer chuck is closed.

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H01L 21/00; C25D 7/12

IPC 8 full level
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Citation (search report)
See references of WO 0033356A2

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WO 0033356 A2 20000608; WO 0033356 A3 20010712; WO 0033356 A9 20010802; AU 3105400 A 20000619; CA 2352160 A1 20000608; CN 100382235 C 20080416; CN 1191605 C 20050302; CN 1346510 A 20020424; CN 1632914 A 20050629; EP 1133786 A2 20010919; IL 143316 A0 20020421; IL 143316 A 20050320; JP 2002531702 A 20020924; JP 2007119923 A 20070517; KR 100503553 B1 20050726; KR 100516776 B1 20050926; KR 100562011 B1 20060322; KR 20010086051 A 20010907; KR 20040070317 A 20040806; KR 20050013179 A 20050202; TW 430919 B 20010421

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